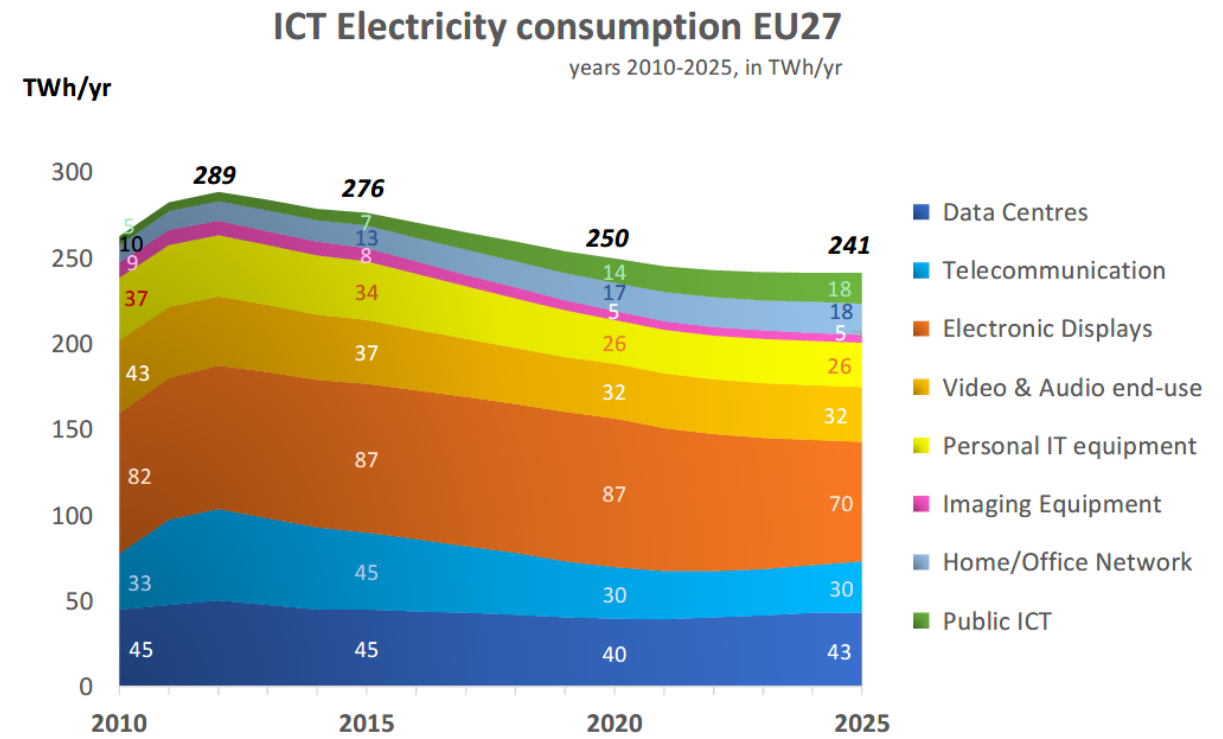
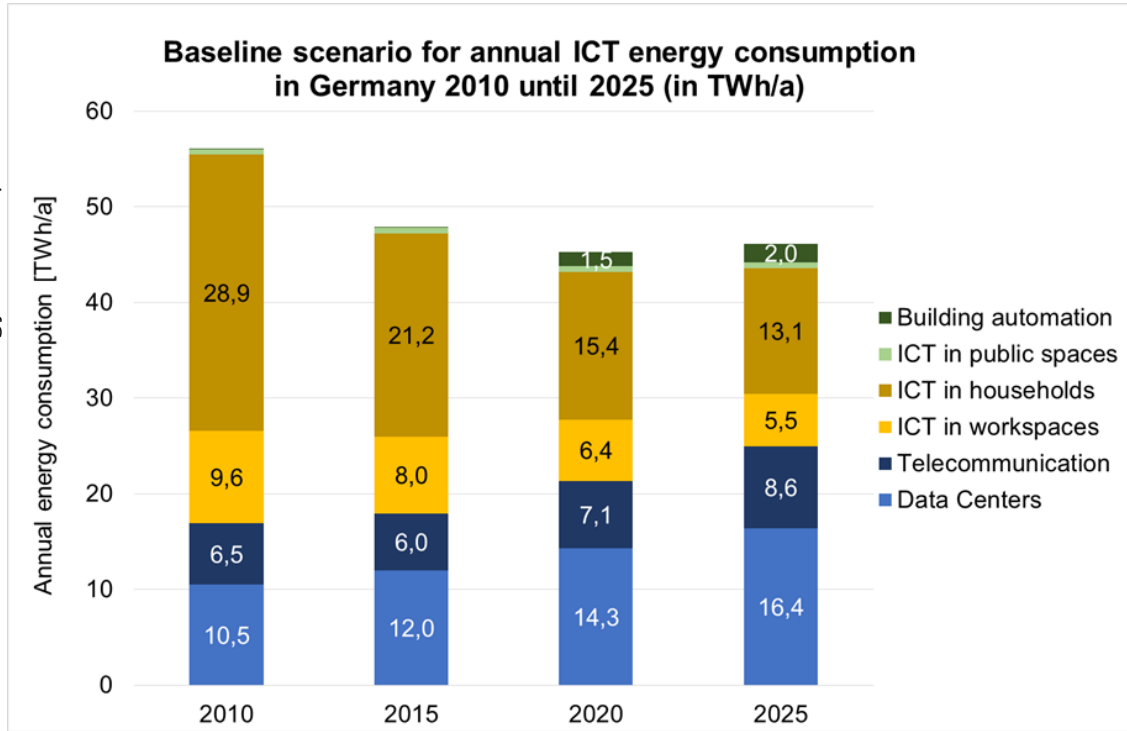


# Green ICT @ FMD

## New German Competence Centre within the Research Fab Microelectronics Germany (FMD)



BMW i / IZM (2014): ICT energy consumption in Germany



VHK and Viegand Maagoe (2020): ICT Impact Study

- ⌘ Positive decrease of ICT power consumption in Europe
- ⌘ Based on our projection (Germany) ICT infrastructure is increasing
- ⌘ Note: Manufacturing footprint not included





Source: Project Utamo, Fraunhofer IZM for:

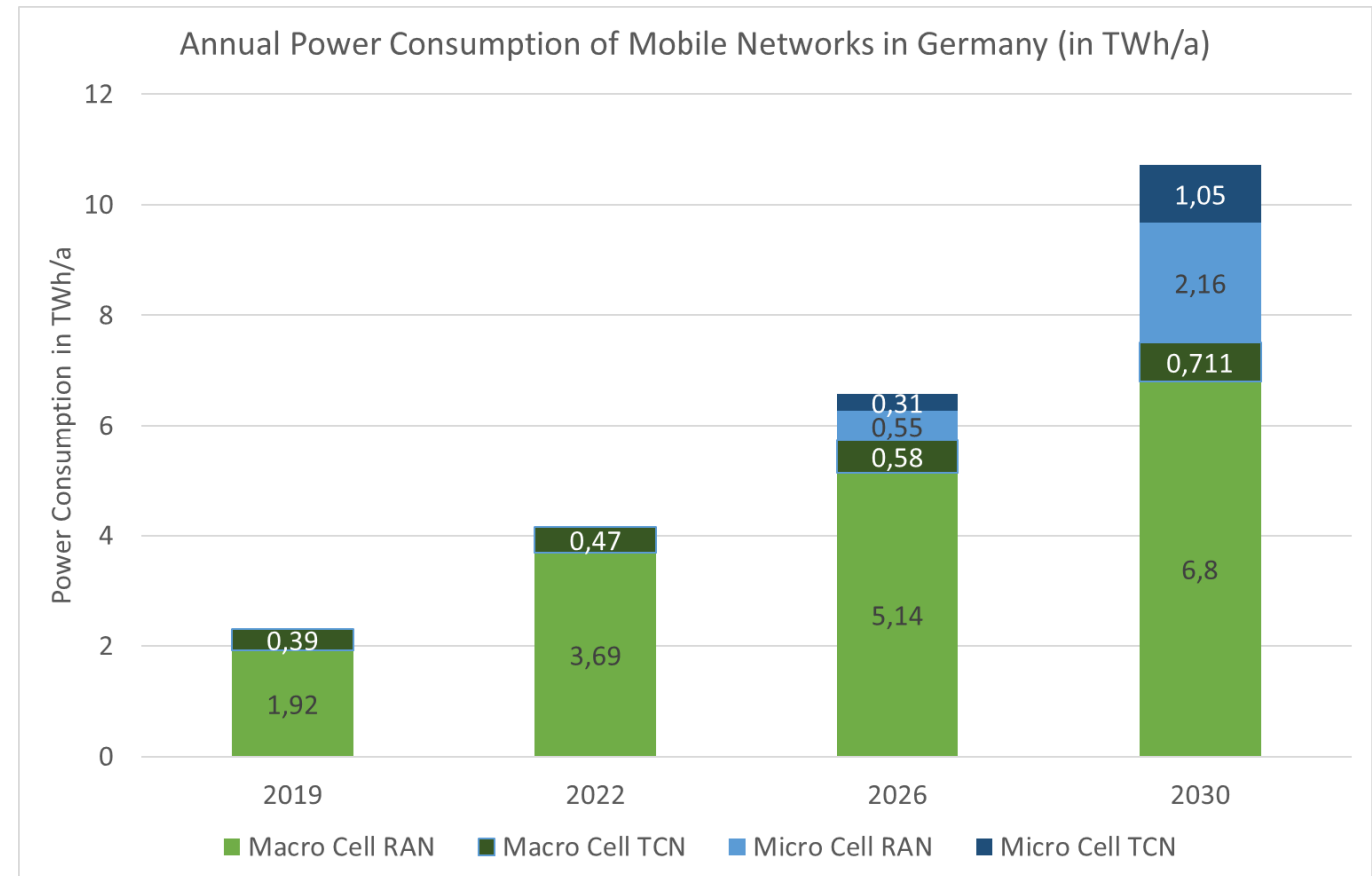


## Macro Cells (cm-wave):

- Outdoor antenna sites (DTAG, Vodafone, Telefonica)
- Existing spectrum 700 MHz – 3,6 GHz (2G – 5G)
- Increase from 85.000 to 120.000 antenna sites
- 100% area coverage (357.386 km<sup>2</sup>)

## Micro Cells (mm-wave):

- Outdoor use in public spaces (eMMB / Hotspot)
- New spectrum 26 – 28 GHz (5G) with average range of around 150 meters
- 245,000 sites with two 60° sectors
- 1% area coverage (3.573 km<sup>2</sup>)



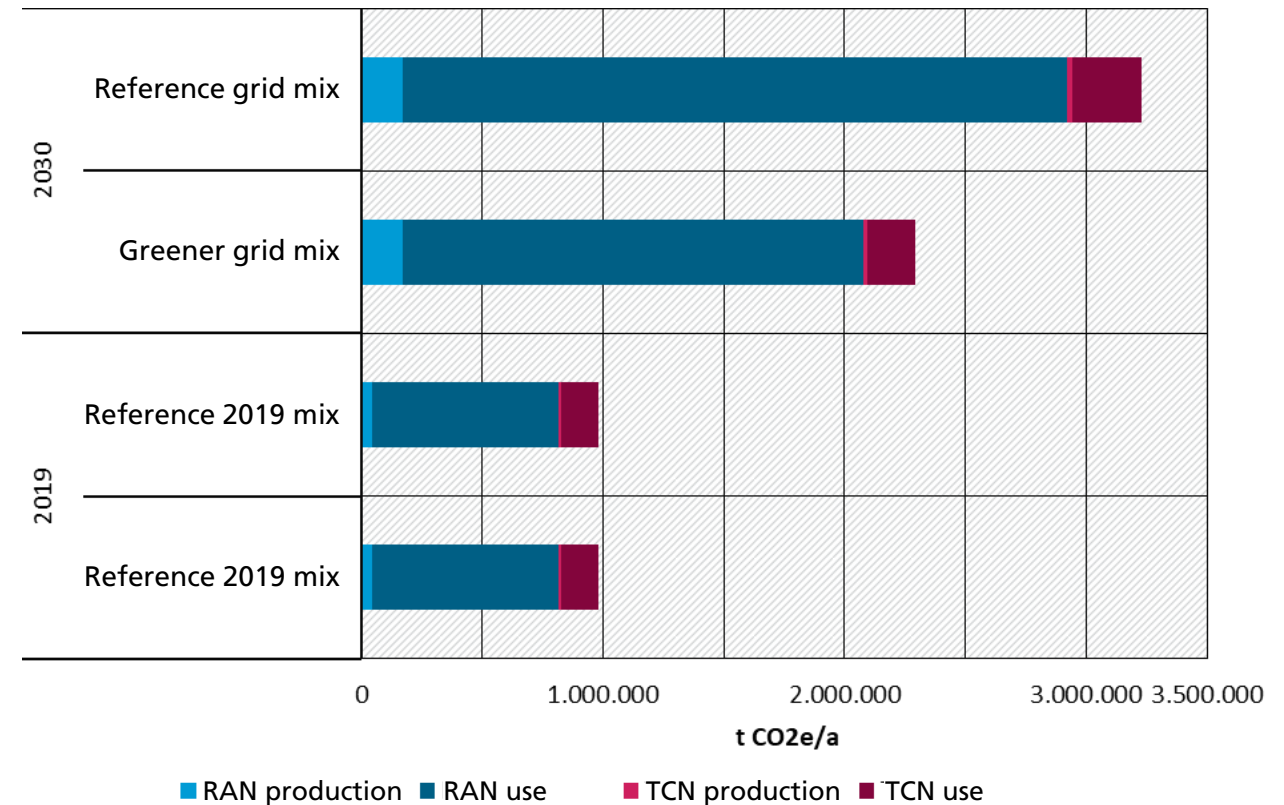
RAN (Radio Access Network) TCN (Transport Core Network)



Source: Project Utamo, Fraunhofer IZM for:



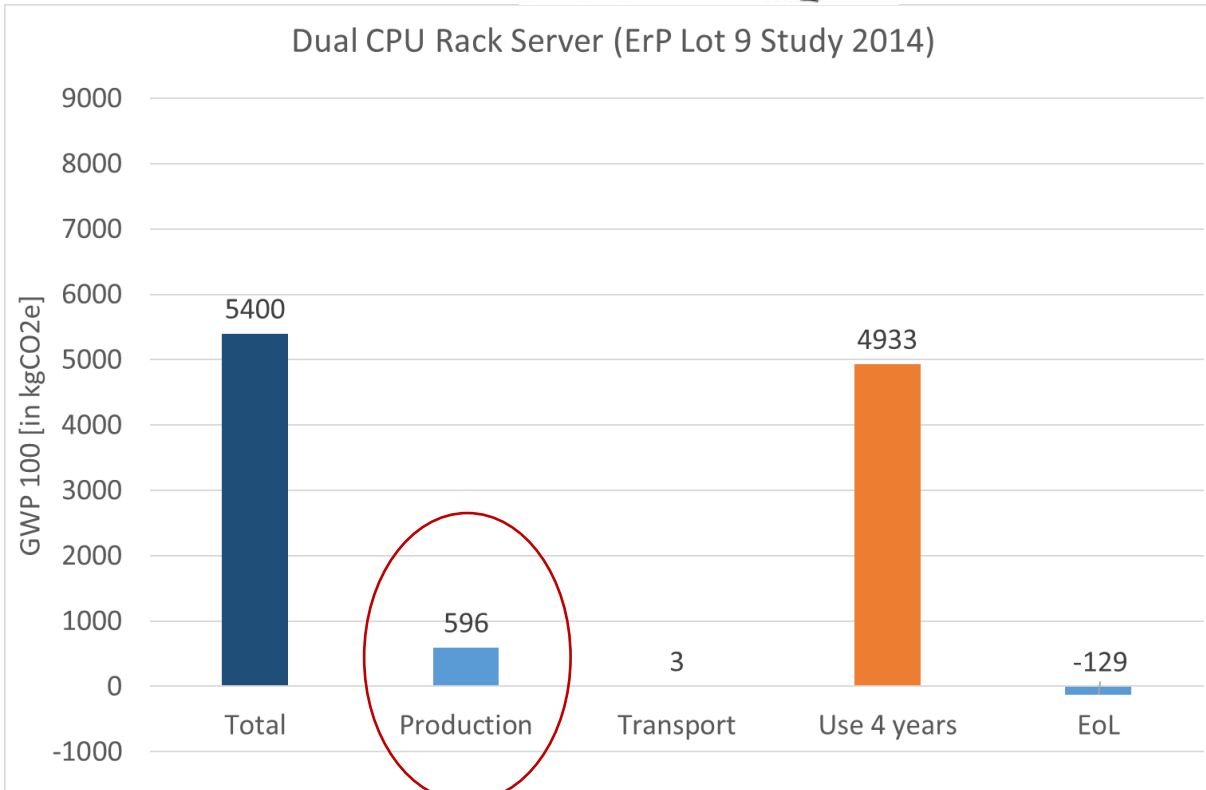
- Adding manufacturing footprint and two energy transition scenarios
  - Note: 2030 scenario provides **factor 45** higher performance
- Two energy mixes for 2030 in Germany (0,4 kg/CO2e and 0,28 kg/CO2e)
- For the network, manufacturing is <10% of carbon footprint
- Efficient components and better load management important



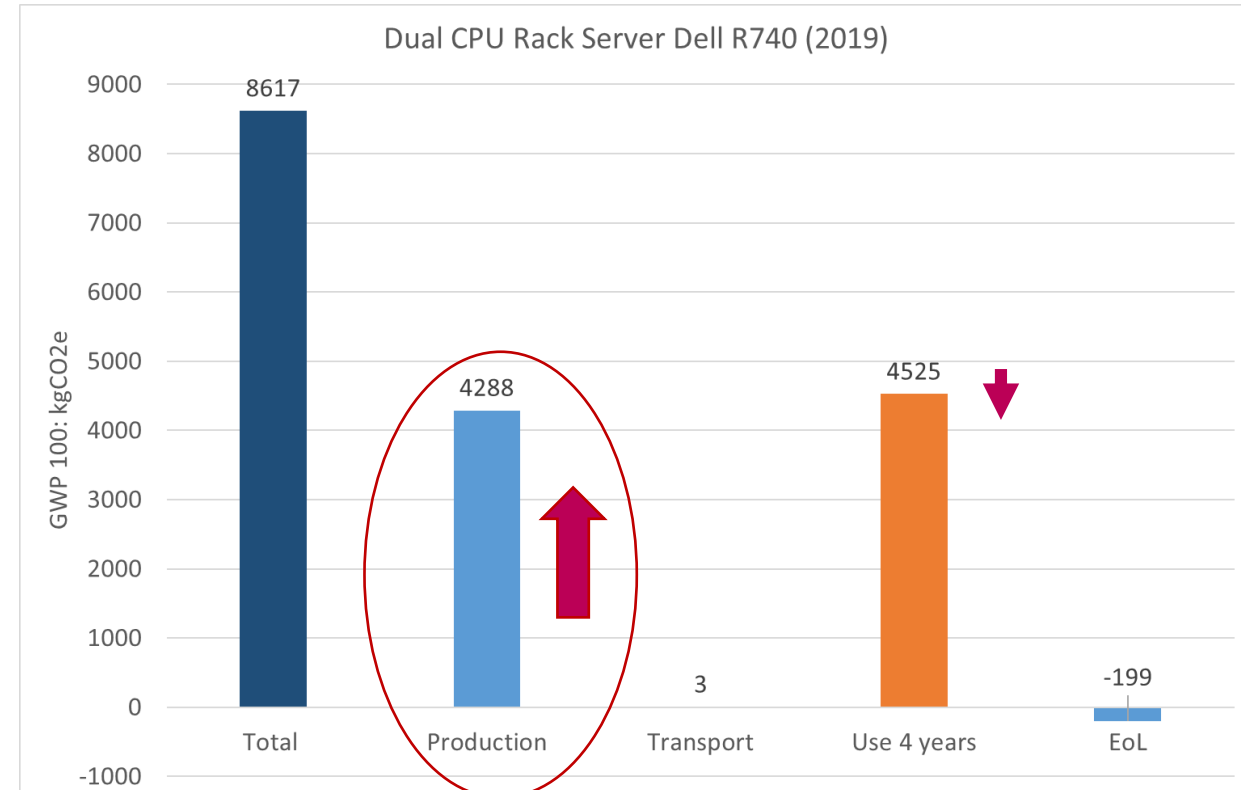
# Servers (Small and Co-location Data Centres)



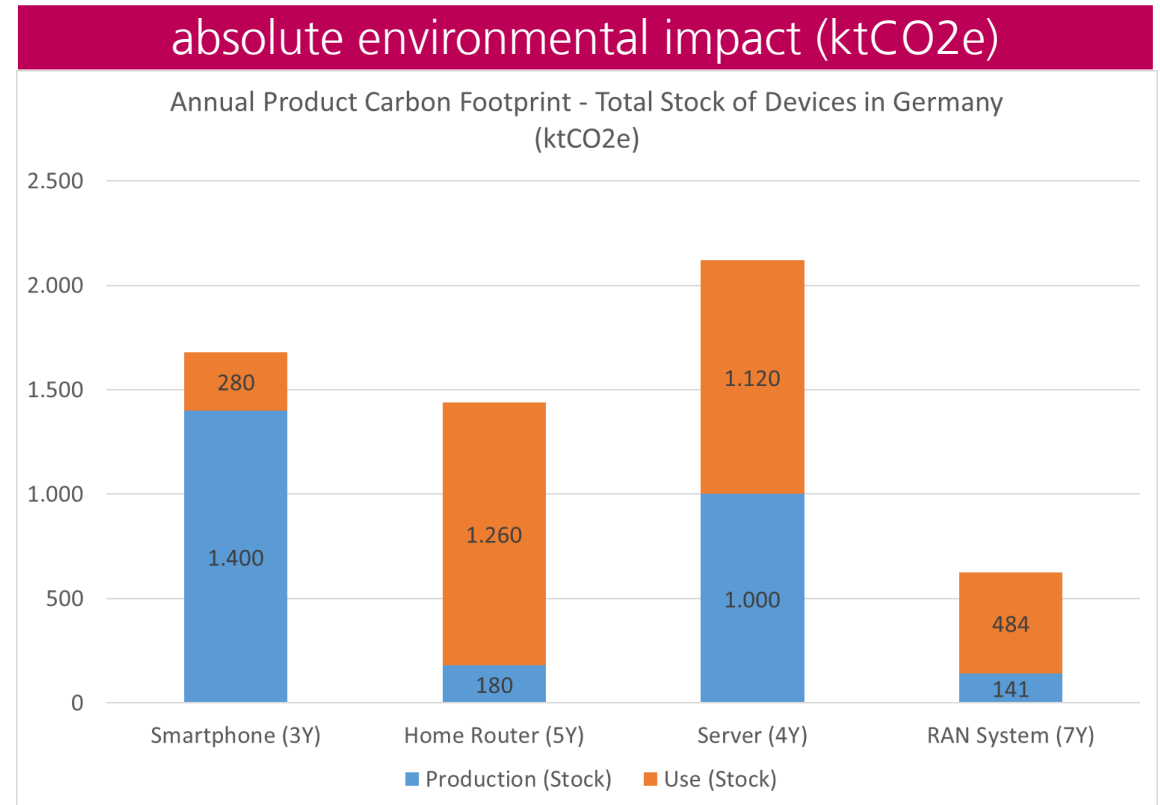
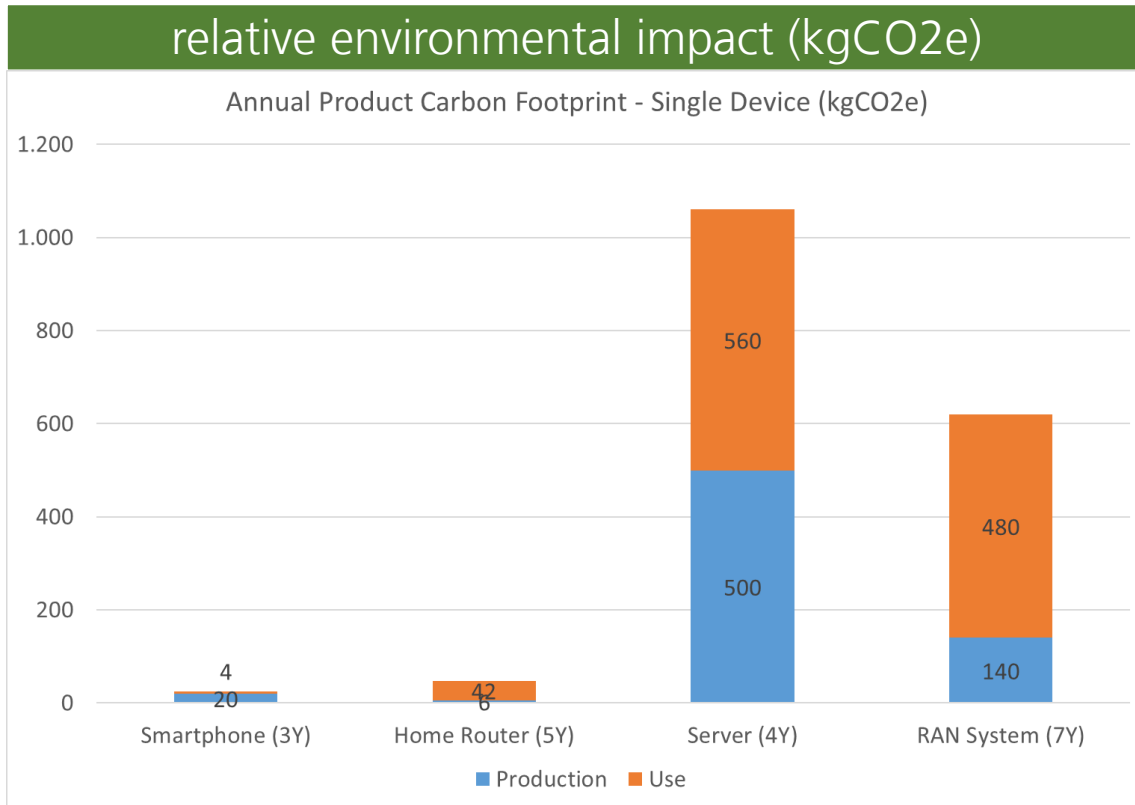
Dual CPU Rack Server (ErP Lot 9 Study 2014)



Dual CPU Rack Server Dell R740 (2019)



⚡ for memory heavy (AI-optimized) servers: carbon footprint of production is higher than for 4 years of use



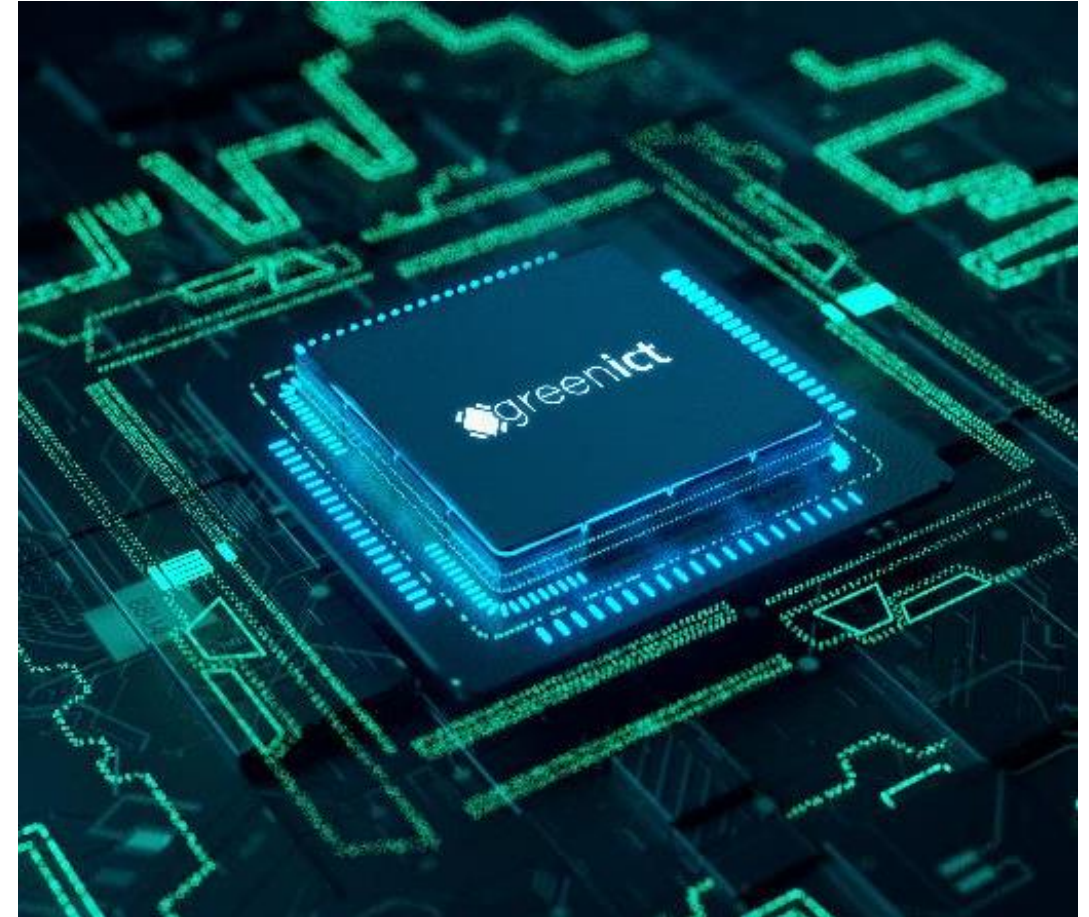
- Relative: single product annual carbon footprint
- Absolute: product stock annual carbon footprint

/// Absolute impact reduction needed

Stock Germany	Devices
70.000.000	Smartphone (3Y)
30.000.000	Home Router (5Y)
2.000.000	Server (4Y)
1.008.000	RAN System (7Y)



- /// We need an ecosystem of R&D to develop, evaluate and roll out validated Green ICT solutions
- /// Focus on leverage of the German market, but many components and products are sourced globally
- /// »Green-by-ICT« may increase leverage positively
- /// but focus must be on **Hardware level improvements** (materials, technologies, components, system integration)





- Research Fab FMD covers 11 micro-electronics institutes of the Fraunhofer Society plus two institutes of Leibnitz (IHP, Frankfurt Oder, and FBH, Berlin)
- Original FMD coordinated investment in new cleanroom processes and heterogenous system integration
- Competence centre »Green ICT« started in 2022 based on same distributed fab cooperation



## »Going Green for ICT Hardware«

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- /// One-stop-shop for green questions
- /// Three core ICT areas
  - /// Sensor-Edge-Cloud
  - /// Communication Networks
  - /// Resource Efficient Production
- /// Additional elements
  - /// Student academy
  - /// Professional development
  - /// Green ICT Start-up Collaborations



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- Focus of production activities
  - Front-end (semiconductor) processing for variety of components, i.e. CMOS, non-CMOS silicon, MEMS, III/V semiconductors
  - Back-end processes: heterogenous packaging including wafer level packaging (WLP), panel level packaging (PLP); multi-chip / chiplet and 3D packages
  - Clean room infrastructure and operations improvements
  - Emissions control and abatement
  - System integration elements, including printed circuit boards
  - Material efficiency and/or substitutions of critical materials



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- /// Take-away messages ...  
... before deeper dive into emissions abatement
- /// Establishment of German knowledge hub for Green ICT
- /// **Production and hardware focussed,**  
where the electronics industry must fundamentally reinvent itself
- /// Partner for small and large enterprises
- /// Partner along the microelectronics supply chain
- /// Material efficiency in parallel to carbon reduction

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# Any Questions?



 **Forschungsfabrik  
Mikroelektronik**  
Deutschland

 **greenict**  
Forschungsfabrik Mikroelektronik Deutschland

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